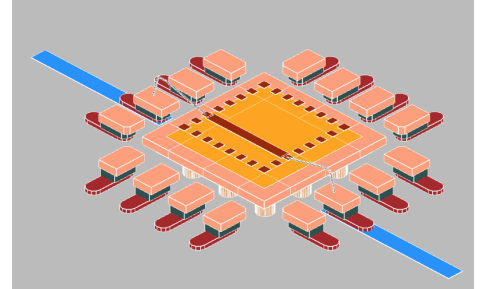


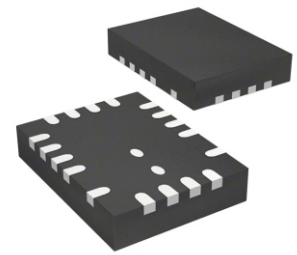
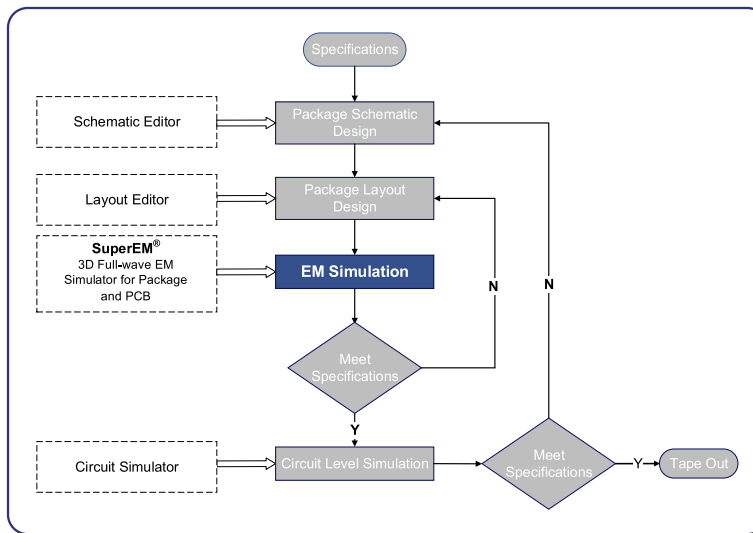


## Introduction

SuperEM<sup>®</sup>, the package and PCB EM simulation software from Faraday Dynamics, Ltd. adopts the most advanced 3D full-wave EM simulation technology for analyzing the electromagnetic field effects of high-speed IC packages and PCBs. It can be seamlessly integrated with the industry's leading package and PCB design environments to provide high-precision EM analysis services to attack very complex EM challenges with gold-standard precision. This reference case demonstrates the SuperEM<sup>®</sup> S-parameter simulation task of a Quad Flat No-leads (QFN)

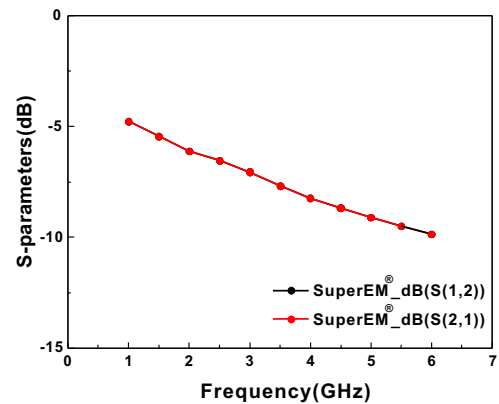
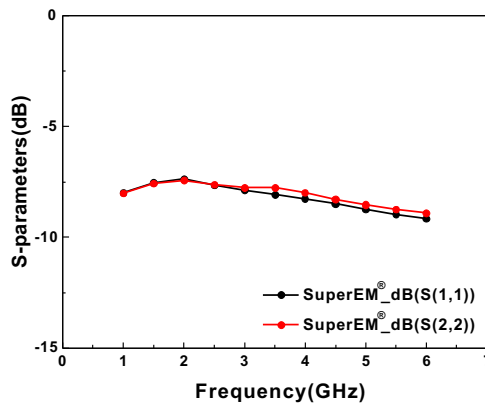


## Design Flow



The QFN package boasts excellent electrical and thermal properties, as well as compact size, lightweight, and low cost. Typically, the chip and packaging components are connected with bonding wires.

## Simulation Results



This example case demonstrates the simulation of a QFN packaging model using SuperEM<sup>®</sup>. SuperEM<sup>®</sup> provides a user-friendly interface for process parameters configuration, layout import, port creation, etc. It can satisfy user's needs for rapid modeling and simulation of packaging design scenarios.

